

MAX3232E-Q1 Automotive 3V TO 5.5V Multichannel RS-232 Line Driver and Receiver WITH $\pm 15\text{kV}$ IEC ESD Protection

1 Features

- Qualified for automotive applications
- Meets or exceeds the requirements of TIA/EIA-232-F and ITU v.28 standards
- Operates with 3V to 5.5V V_{CC} supply
- Operates up to 250kbit/s
- Two drivers and two receivers
- Low standby current: 300 μA Typical
- External capacitors: $4 \times 0.1\mu\text{F}$
- Accepts 5V logic input with 3.3V supply
- Pin compatible to alternative high-speed pin-compatible device (1Mbit/s): SNx5C3232

2 Applications

- [Industrial PCs](#)
- [Wired networking](#)
- [Data center and enterprise computing](#)
- [Battery-powered systems](#)
- [Notebooks](#)
- [Palmtop PCs](#)
- [Hand-held equipment](#)

3 Description

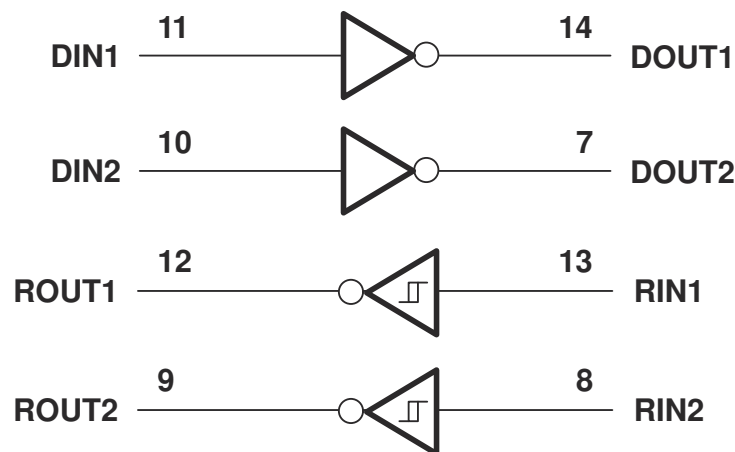
The MAX3232E device consists of two line drivers, two line receivers, and a dual charge-pump circuit with $\pm 15\text{kV}$ IEC ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3V to 5.5V supply. The device operates at data signaling rates up to 250kbit/s and a maximum of $30\text{V}/\mu\text{s}$ driver output slew rate.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
MAX3232E	PW (TSSOP, 16)	5mm x 6.4mm

(1) For more information, see [Section 9](#).

(2) The package size (length $\times$ width) is a nominal value and includes pins, where applicable.



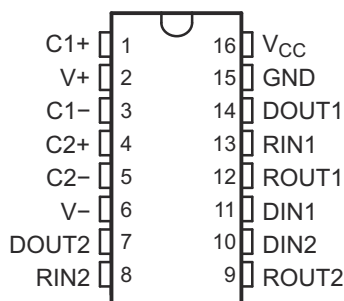
Logic Diagram (Positive Logic)



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4 Pin Configuration and Functions



**Figure 4-1. PW Package
(Top View)**

Table 4-1. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
C1+	1	—	Positive lead of C1 capacitor
V+	2	O	Positive charge pump output for storage capacitor only
C1–	3	—	Negative lead of C1 capacitor
C2+	4	—	Positive lead of C2 capacitor
C2–	5	—	Negative lead of C2 capacitor
V–	6	O	Negative charge pump output for storage capacitor only
DOUT2	7	O	RS232 line data output (to remote RS232 system)
RIN2	8	I	RS232 line data input (from remote RS232 system)
ROUT2	9	O	Logic data output (to UART)
DIN2	10	I	Logic data input (from UART)
DIN1	11	I	Logic data input (from UART)
ROUT1	12	O	Logic data output (to UART)
RIN1	13	I	RS232 line data input (from remote RS232 system)
DOUT1	14	O	RS232 line data output (to remote RS232 system)
GND	15	—	Ground
V _{CC}	16	—	Supply Voltage, Connect to external 3V to 5.5V power supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage range ⁽²⁾		−0.3	6	V
V+	Positive output supply voltage range ⁽²⁾		−0.3	7	V
V−	Negative output supply voltage range ⁽²⁾		0.3	−7	V
V+ − V−	Supply voltage difference ⁽²⁾			13	V
V _I	Input voltage range	Drivers	−0.3	6	V
		Receivers	−25	25	V
V _O	Output voltage range	Drivers	−13.2	13.2	V
		Receivers	−0.3	V _{CC} + 0.3	V
T _J	Operating virtual junction temperature			150	°C
T _{stg}	Storage temperature range		−65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.

5.2 Recommended Operating Conditions

see Figure 6-1 ⁽¹⁾

				MIN	NOM	MAX	UNIT
Supply voltage		V _{CC} = 3.3V		3	3.3	3.6	V
		V _{CC} = 5V		4.5	5	5.5	
V _{IH}	Driver high-level input voltage	DIN	V _{CC} = 3.3V	2		5.5	V
			V _{CC} = 5V	2.4		5.5	
V _{IL}	Driver low-level input voltage	DIN		0		0.8	V
V _I	Receiver input voltage			−25		25	V
T _A	Operating free-air temperature	MAX3232I		−40		85	°C

- (1) Test conditions are C1–C4 = 0.1μF at V_{CC} = 3.3V ± 0.3V; C1 = 0.047μF, C2–C4 = 0.33μF at V_{CC} = 5V ± 0.5V.

5.3 Thermal Information

THERMAL METRIC ⁽¹⁾		TSSOP (PW)	UNIT
		16-Pins	
R _{θJA}	Junction-to-ambient thermal resistance	108	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.4 Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6-1)

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
I _{CC} Supply current	No load, V _{CC} = 3.3V or 5V		0.3	1	mA

- (1) Test conditions are C1–C4 = 0.1μF at V_{CC} = 3.3V ± 0.3V; C1 = 0.047μF, C2–C4 = 0.33μF at V_{CC} = 5V ± 0.5V.
- (2) All typical values are at V_{CC} = 3.3V or V_{CC} = 5V and T_A = 25°C.

5.5 Driver Section, Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH} High-level output voltage	DOUT at R _L = 3kΩ to GND, DIN = GND	5	5.4		V
V _{OL} Low-level output voltage	DOUT at R _L = 3kΩ to GND, DIN = V _{CC}		–5.4	–5	V
I _{IH} High-level input current	V _I = V _{CC}		±0.01	±1	μA
I _{IL} Low-level input current	V _I at GND		±0.01	±1	μA
I _{OS} Short-circuit output current ⁽³⁾	V _{CC} = 3.6V, V _O = 0V		±35	±60	mA
	V _{CC} = 5.5V, V _O = 0V				
r _o Output resistance	V _{CC} , V ₊ , and V _– = 0V, V _O = 2V	300	10M		Ω

(1) Test conditions are C1–C4 = 0.1μF at V_{CC} = 3.3V ± 0.3V; C1 = 0.047μF, C2–C4 = 0.33μF at V_{CC} = 5V ± 0.5V.

(2) All typical values are at V_{CC} = 3.3V or V_{CC} = 5V and T_A = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

5.6 Driver Section, Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
Maximum data rate	C _L = 1000pF, One DOUT switching, R _L = 3kΩ, See Figure 6-1	150	250		kbit/s
t _{sk(p)} Pulse skew ⁽³⁾	C _L = 150pF to 2500pF, R _L = 3kΩ to 7kΩ, See Figure 6-2		300		ns
SR(tr) Slew rate, transition region (see Figure 6-1)	R _L = 3kΩ to 7kΩ, V _{CC} = 3.3V	6		30	v/μs
	C _L = 150pF to 1000pF	4		30	

(1) Test conditions are C1–C4 = 0.1μF at V_{CC} = 3.3V ± 0.3V; C1 = 0.047μF, C2–C4 = 0.33μF at V_{CC} = 5V ± 0.5V.

(2) All typical values are at V_{CC} = 3.3V or V_{CC} = 5V and T_A = 25°C.

(3) Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

5.7 Receiver Section, Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = –1mA	V _{CC} – 0.6V	V _{CC} – 0.1V		V
V _{OL} Low-level output voltage	I _{OL} = 1.6mA			0.4	V
V _{IT+} Positive-going input threshold voltage	V _{CC} = 3.3V		1.5	2.4	V
	V _{CC} = 5V		1.8	2.4	
V _{IT–} Negative-going input threshold voltage	V _{CC} = 3.3V	0.6	1.2		V
	V _{CC} = 5V	0.8	1.5		
V _{hys} Input hysteresis (V _{IT+} – V _{IT–})			0.3		V
r _I Input resistance	V _I = ±3V to ±25	3	5	7	kΩ

(1) Test conditions are C1–C4 = 0.1μF at V_{CC} = 3.3V ± 0.3V; C1 = 0.047μF, C2–C4 = 0.33μF at V_{CC} = 5V ± 0.5V.

(2) All typical values are at V_{CC} = 3.3V or V_{CC} = 5V and T_A = 25°C.

5.8 Receiver Section, Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6-3](#))

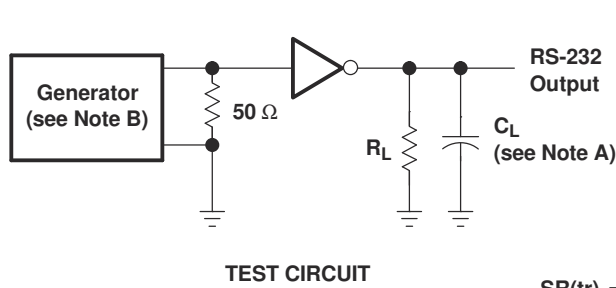
PARAMETER		TEST CONDITIONS ⁽¹⁾	TYP ⁽²⁾	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	$C_L = 150\text{pF}$	300	ns
t_{PHL}	Propagation delay time, high- to low-level output	$C_L = 150\text{pF}$	300	ns
$t_{sk(p)}$	Pulse skew ⁽³⁾		300	ns

(1) Test conditions are $C1-C4 = 0.1\mu\text{F}$ at $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$; $C1 = 0.047\mu\text{F}$, $C2-C4 = 0.33\mu\text{F}$ at $V_{CC} = 5\text{V} \pm 0.5\text{V}$.

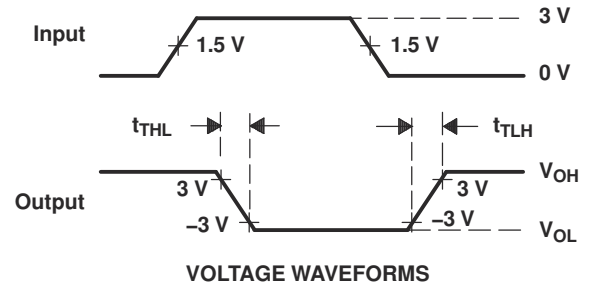
(2) All typical values are at $V_{CC} = 3.3\text{V}$ or $V_{CC} = 5\text{V}$ and $T_A = 25^\circ\text{C}$.

(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

Parameter Measurement Information

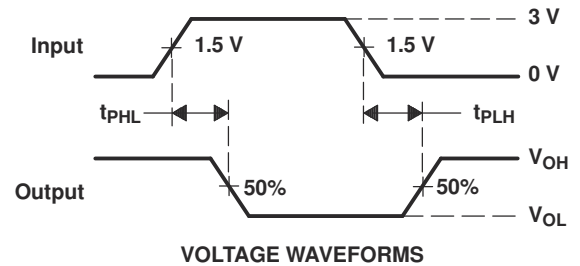
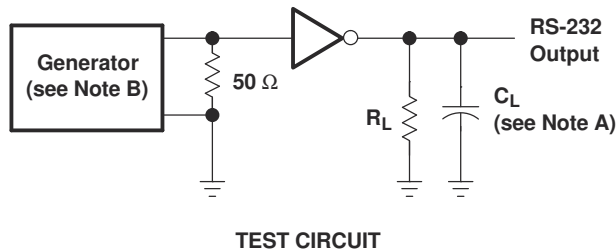


$$SR(tr) = \frac{6\text{ V}}{t_{THL} \text{ or } t_{TLH}}$$



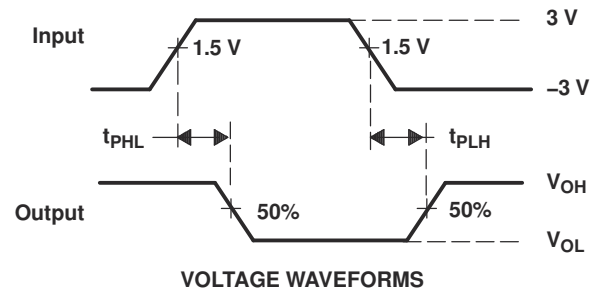
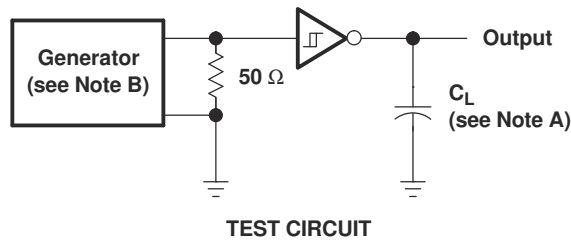
- A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250kbit/s, $Z_O = 50\Omega$, 50% duty cycle, $t_r \leq 10\text{ns}$, $t_f \leq 10\text{ns}$.

Figure 6-1. Driver Slew Rate



- A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250kbit/s, $Z_O = 50\Omega$, 50% duty cycle, $t_r \leq 10\text{ns}$, $t_f \leq 10\text{ns}$.

Figure 6-2. Driver Pulse Skew



- A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $Z_O = 50\Omega$, 50% duty cycle, $t_r \leq 10\text{ns}$, $t_f \leq 10\text{ns}$.

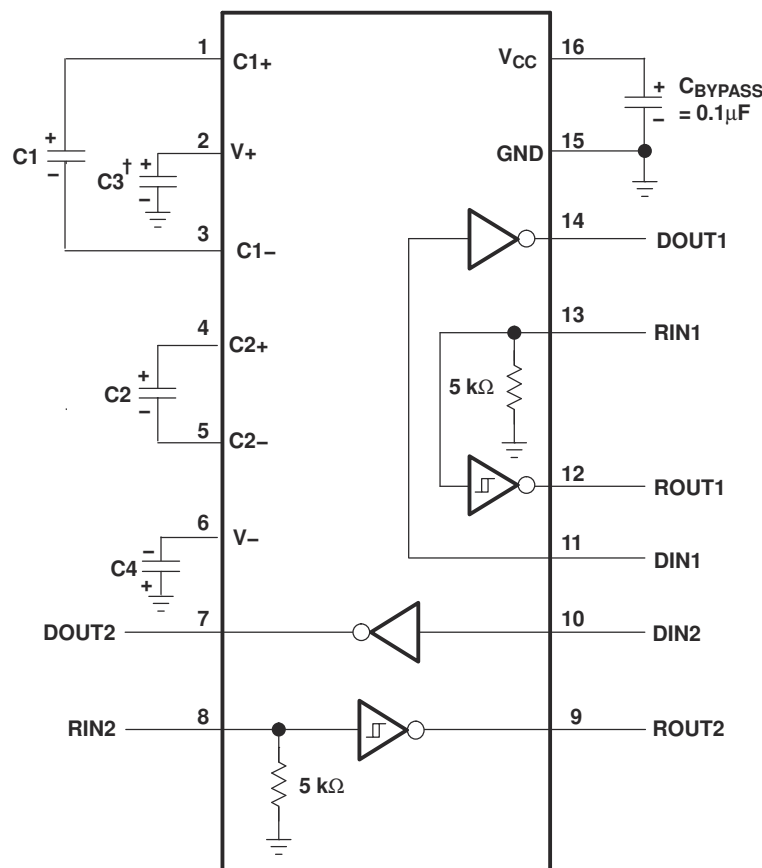
Figure 6-3. Receiver Propagation Delay Times

6 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

Typical Application



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, C4
3.3 V $\pm$ 0.3 V	0.1 μ F	0.1 μ F
5 V $\pm$ 0.5 V	0.047 μ F	0.33 μ F
3 V to 5.5 V	0.1 μ F	0.47 μ F

Figure 6-1. Typical Operating Circuit and Capacitor Values

7 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

7.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

7.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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7.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
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7.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

8 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (February 2008) to Revision B (December 2024)	Page
• Changed the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added the <i>Thermal Information</i> table.....	4
• Changed V_{OL} : moved –5V from the MIN to the MAX column in <i>Driver Section, Electrical Characteristics</i>	5

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX3232EIPWRQ1	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3232I
MAX3232EIPWRQ1.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3232I
MAX3232EIPWRQ1.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3232I

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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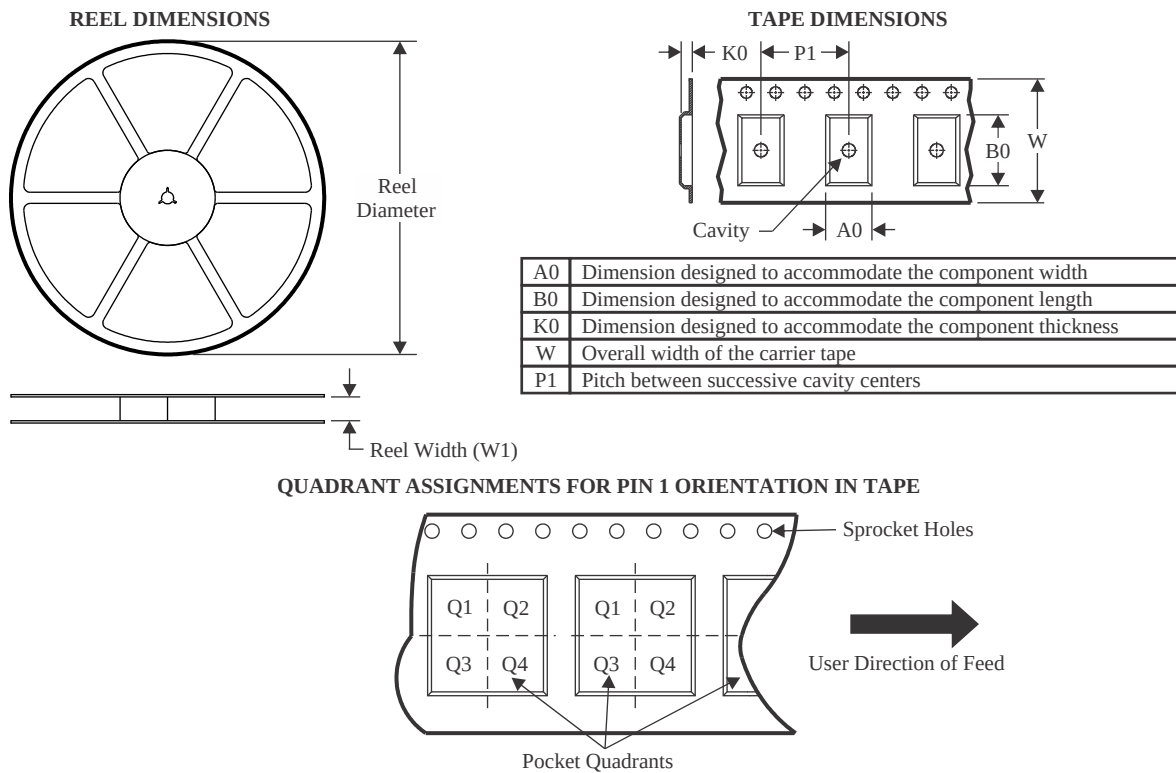
OTHER QUALIFIED VERSIONS OF MAX3232E-Q1 :

- Catalog : [MAX3232E](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

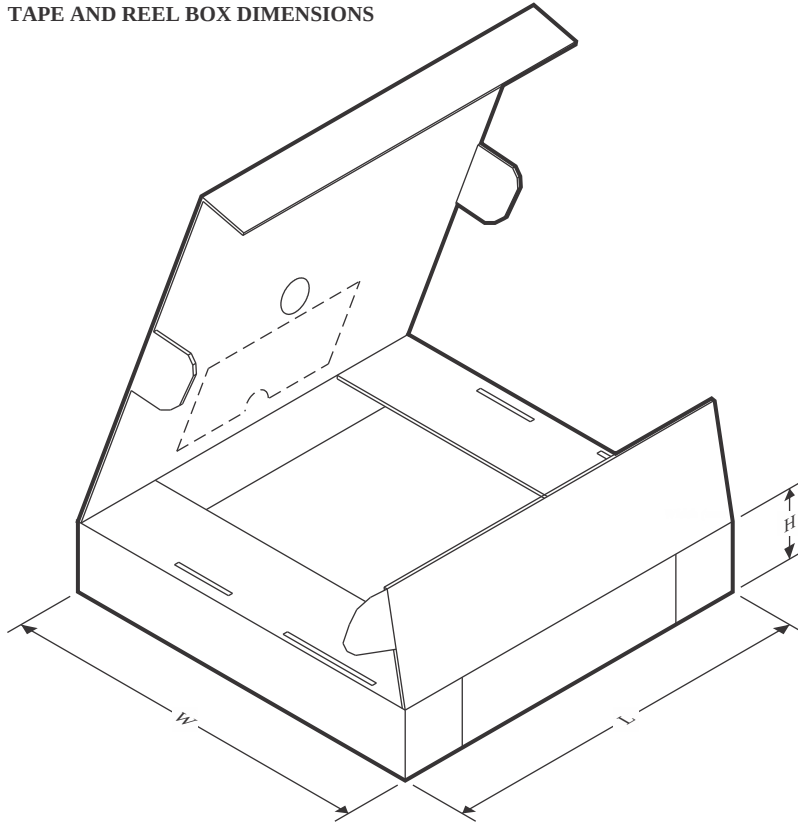
TAPE AND REEL INFORMATION



*All dimensions are nominal

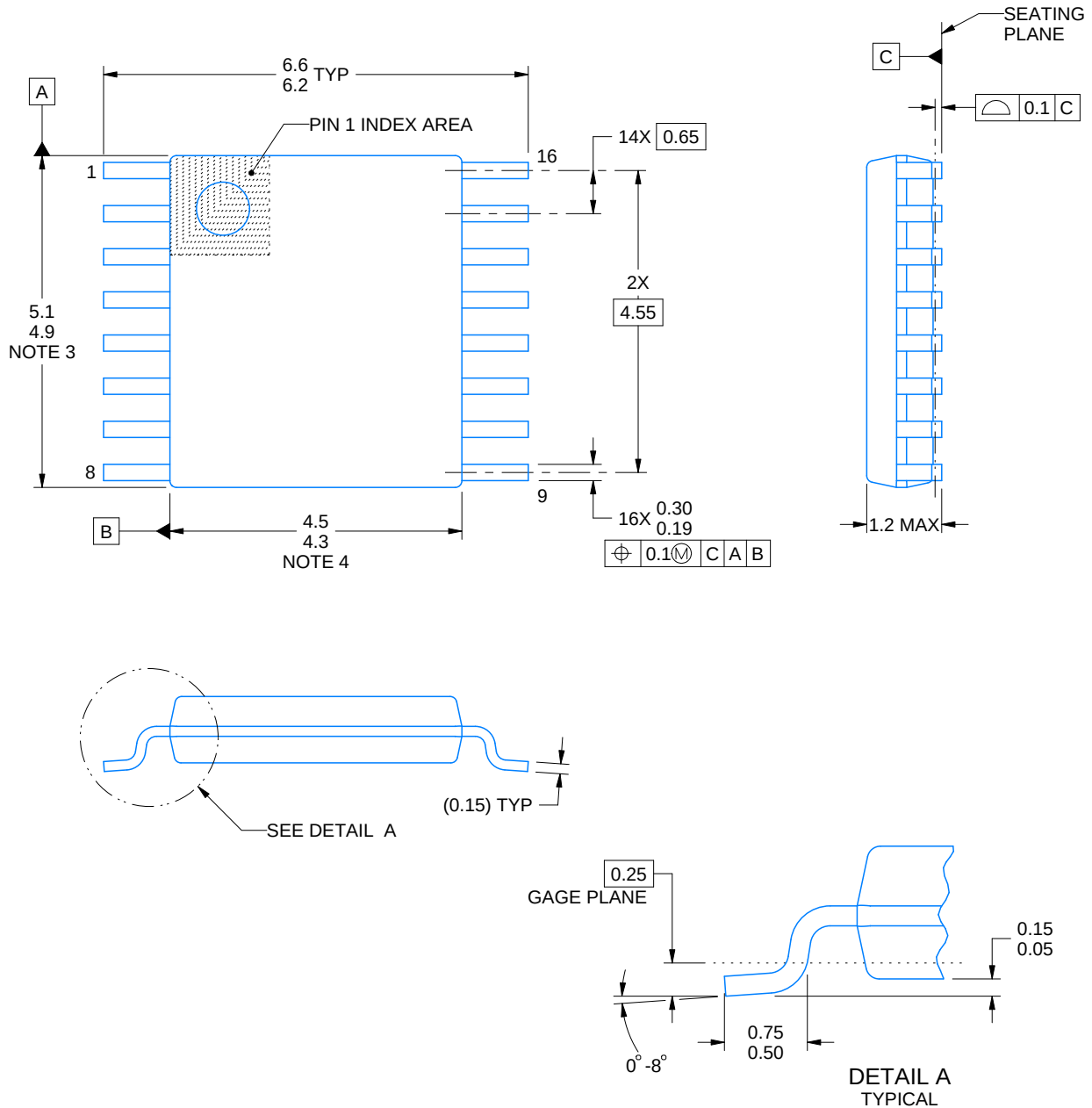
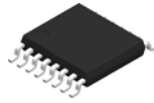
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3232EIPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3232EIPWRQ1	TSSOP	PW	16	2000	356.0	356.0	35.0



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NOTES:

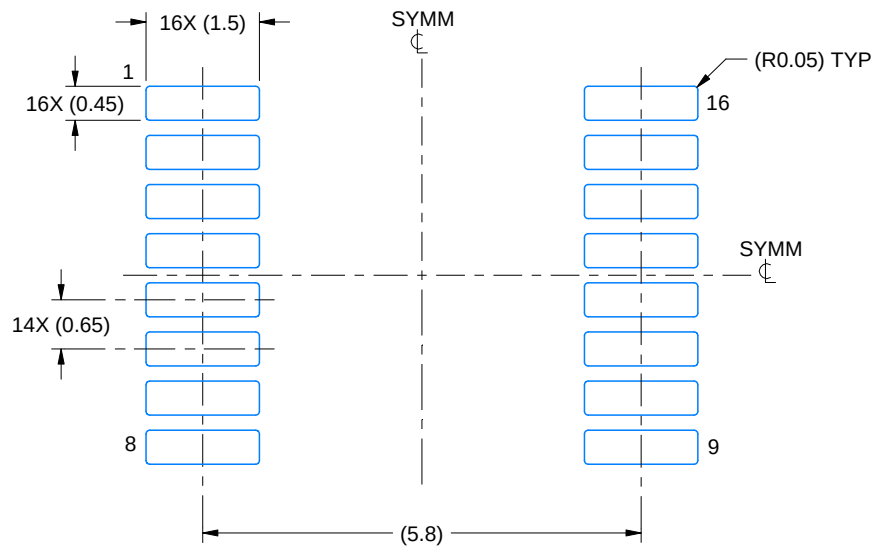
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

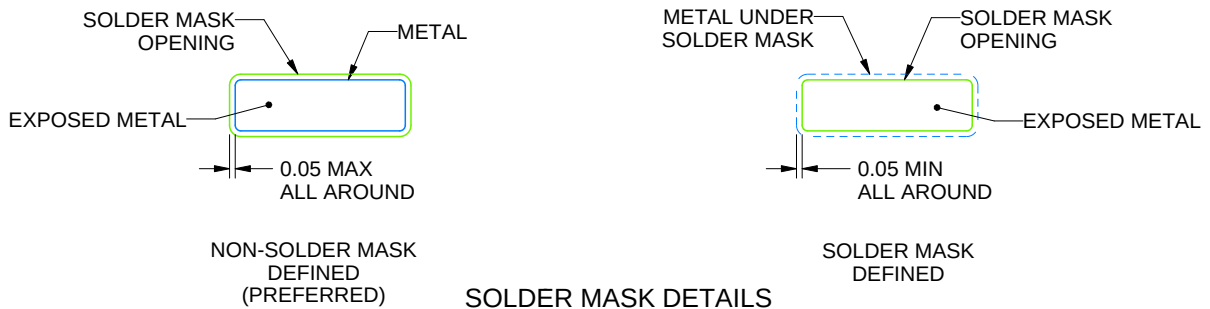
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

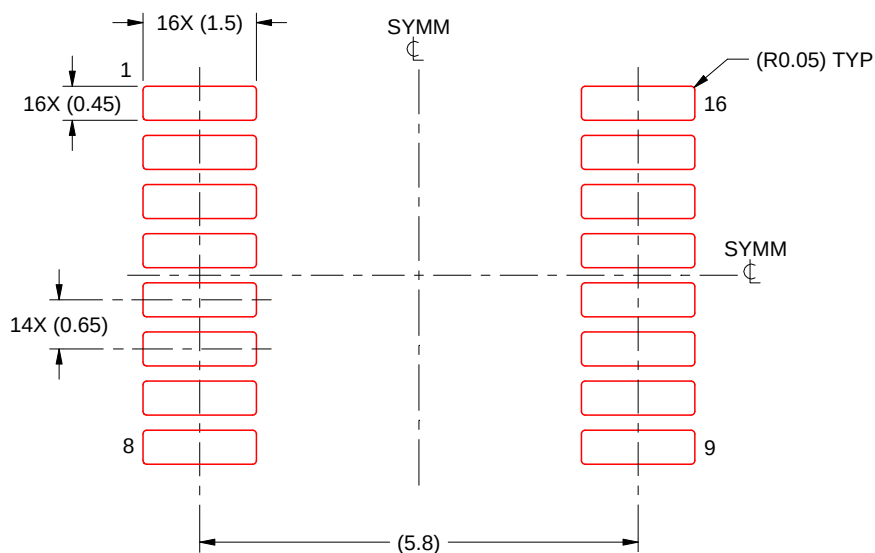
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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